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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Not For New Designs
Core Processor	8051
Core Size	8-Bit
Speed	100MHz
Connectivity	EBI/EMI, SMBus (2-Wire/I ² C), SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, Temp Sensor, WDT
Number of I/O	32
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8.25K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 8x8b, 8x10b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f123-gq

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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		Pin Nu	mbers			
Name	ʻF120 ʻF122 ʻF124 ʻF126	'F121 'F123 'F125 'F127	'F130 'F132	'F131 'F133	Туре	Description
AD0/D0/P3.0	54	47	54	47	D I/O	Bit 0 External Memory Address/Data bus (Multi- plexed mode) Bit 0 External Memory Data bus (Non-multi- plexed mode) Port 3.0 See Port Input/Output section for complete description.
AD1/D1/P3.1	53	46	53	46	D I/O	Port 3.1. See Port Input/Output section for complete description.
AD2/D2/P3.2	52	45	52	45	D I/O	Port 3.2. See Port Input/Output section for com- plete description.
AD3/D3/P3.3	51	44	51	44	D I/O	Port 3.3. See Port Input/Output section for complete description.
AD4/D4/P3.4	50	43	50	43	D I/O	Port 3.4. See Port Input/Output section for complete description.
AD5/D5/P3.5	49	42	49	42	D I/O	Port 3.5. See Port Input/Output section for complete description.
AD6/D6/P3.6	48	39	48	39	D I/O	Port 3.6. See Port Input/Output section for complete description.
AD7/D7/P3.7	47	38	47	38	D I/O	Port 3.7. See Port Input/Output section for com- plete description.
P4.0	98		98		D I/O	Port 4.0. See Port Input/Output section for complete description.
P4.1	97		97		D I/O	Port 4.1. See Port Input/Output section for complete description.
P4.2	96		96		D I/O	Port 4.2. See Port Input/Output section for complete description.
P4.3	95		95		D I/O	Port 4.3. See Port Input/Output section for complete description.
P4.4	94		94		D I/O	Port 4.4. See Port Input/Output section for complete description.

Table 4.1. Pin Definitions (Continued)





Figure 4.1. C8051F120/2/4/6 Pinout Diagram (TQFP-100)





Figure 6.6. 10-Bit ADC0 Window Interrupt Example: Right Justified Single-Ended Data



SFR Pag SFR Add	e: 2 ress: 0xBA							
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	-	-	-	PIN67IC	PIN45IC	PIN23IC	PIN01IC	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	<u>_</u>
Bits7–4 Bit3:	UNUSED. R PIN67IC: All 0: AIN2.6 an 1: AIN2.6 an	ead = 0000 \2.6, AIN2. ⁻ d AIN2.7 ar d AIN2.7 ar	b; Write = d 7 Input Pair e independe e (respectiv	on't care. Configuration ent single-ent rely) +, – diff	on Bit. nded inputs ferential inp	ut pair.		
BITZ:	0: AIN2.4 an 1: AIN2.4 an	d AIN2.5 ar d AIN2.5 ar d AIN2.5 ar	e independe e (respectiv	ent single-e rely) +, – diff	nded inputs ferential inp	ut pair.		
Bit1:	PIN23IC: All 0: AIN2.2 an 1: AIN2.2 an	V2.2, AIN2.3 d AIN2.3 ar d AIN2.3 ar	3 Input Pair e independe e (respectiv	Configuration ent single-en rely) +, – diff	on Bit. nded inputs ferential inp	ut pair.		
Bit0:	PIN01IC: AIN 0: AIN2.0 an 1: AIN2.0 an	12.0, AIN2. d AIN2.1 ar d AIN2.1 ar	1 Input Pair e independe e (respectiv	Configuratio ent single-e vely) +, – diff	on Bit. nded inputs ferential inp	ut pair.		
Note:	The ADC2 Data	Word is in 2'	s complemer	nt format for c	hannels con	figured as dii	fferential.	

SFR Definition 7.1. AMX2CF: AMUX2 Configuration



8.1.1. Update Output On-Demand

In its default mode (DAC0CN.[4:3] = '00') the DAC0 output is updated "on-demand" on a write to the highbyte of the DAC0 data register (DAC0H). It is important to note that writes to DAC0L are held, and have no effect on the DAC0 output until a write to DAC0H takes place. If writing a full 12-bit word to the DAC data registers, the 12-bit data word is written to the low byte (DAC0L) and high byte (DAC0H) data registers. Data is latched into DAC0 after a write to the corresponding DAC0H register, **so the write sequence should be DAC0L followed by DAC0H** if the full 12-bit resolution is required. The DAC can be used in 8bit mode by initializing DAC0L to the desired value (typically 0x00), and writing data to only DAC0H (also see **Section 8.2** for information on formatting the 12-bit DAC data word within the 16-bit SFR space).

8.1.2. Update Output Based on Timer Overflow

Similar to the ADC operation, in which an ADC conversion can be initiated by a timer overflow independently of the processor, the DAC outputs can use a Timer overflow to schedule an output update event. This feature is useful in systems where the DAC is used to generate a waveform of a defined sampling rate by eliminating the effects of variable interrupt latency and instruction execution on the timing of the DAC output. When the DACOMD bits (DACOCN.[4:3]) are set to '01', '10', or '11', writes to both DAC data registers (DACOL and DACOH) are held until an associated Timer overflow event (Timer 3, Timer 4, or Timer 2, respectively) occurs, at which time the DACOH:DACOL contents are copied to the DAC input latches allowing the DAC output to change to the new value.

8.2. DAC Output Scaling/Justification

In some instances, input data should be shifted prior to a DAC0 write operation to properly justify data within the DAC input registers. This action would typically require one or more load and shift operations, adding software overhead and slowing DAC throughput. To alleviate this problem, the data-formatting feature provides a means for the user to program the orientation of the DAC0 data word within data registers DAC0H and DAC0L. The three DAC0DF bits (DAC0CN.[2:0]) allow the user to specify one of five data word orientations as shown in the DAC0CN register definition.

DAC1 is functionally the same as DAC0 described above. The electrical specifications for both DAC0 and DAC1 are given in Table 8.1.



NOTES:





Figure 11.1. CIP-51 Block Diagram

Programming and Debugging Support

A JTAG-based serial interface is provided for in-system programming of the Flash program memory and communication with on-chip debug support logic. The re-programmable Flash can also be read and changed by the application software using the MOVC and MOVX instructions. This feature allows program memory to be used for non-volatile data storage as well as updating program code under software control.

The on-chip debug support logic facilitates full speed in-circuit debugging, allowing the setting of hardware breakpoints and watch points, starting, stopping and single stepping through program execution (including interrupt service routines), examination of the program's call stack, and reading/writing the contents of registers and memory. This method of on-chip debug is completely non-intrusive and non-invasive, requiring no RAM, Stack, timers, or other on-chip resources.

The CIP-51 is supported by development tools from Silicon Labs and third party vendors. Silicon Labs provides an integrated development environment (IDE) including editor, macro assembler, debugger and programmer. The IDE's debugger and programmer interface to the CIP-51 via its JTAG interface to provide fast and efficient in-system device programming and debugging. Third party macro assemblers and C compilers are also available.



Interrupt Source	Interru pt Vector	Priority Order	ority der Pending Flags		Cleared by HW?	SFRPAGE (SFRPGEN = 1)	Enable Flag	Priority Control
Comparator 1 Rising Edge	0x006B	13	CP1RIF (CPT1CN.5)	Y		2	ECP1R (EIE1.7)	PCP1F (EIP1.7)
Timer 3	0x0073	14	TF3 (TMR3CN.7) EXF3 (TMR3CN.6)	Y		1	ET3 (EIE2.0)	PT3 (EIP2.0)
ADC0 End of Conversion	0x007B	15	AD0INT (ADC0CN.5)	Y		0	EADC0 (EIE2.1)	PADC0 (EIP2.1)
Timer 4	0x0083	16	TF4 (TMR4CN.7) EXF4 (TMR4CN.7)	Y		2	ET4 (EIE2.2)	PT4 (EIP2.2)
ADC2 Window Comparator	0x008B	17	AD2WINT (ADC2CN.0)	Y		2	EWADC2 (EIE2.3)	PWADC2 (EIP2.3)
ADC2 End of Conversion	0x0093	18	AD2INT (ADC2CN.5)	Y		2	EADC2 (EIE2.4)	PADC2 (EIP2.4)
RESERVED	0x009B	19	N/A	N/A	N/A	N/A	N/A	N/A
UART1	0x00A3	20	RI1 (SCON1.0) TI1 (SCON1.1)	Y		1	ES1 (EIE2.6)	PS1 (EIP2.6)

Table 11.4. Interrupt Summary (Continued)

11.3.3. Interrupt Priorities

Each interrupt source can be individually programmed to one of two priority levels: low or high. A low priority interrupt service routine can be preempted by a high priority interrupt. A high priority interrupt cannot be preempted. Each interrupt has an associated interrupt priority bit in an SFR (IP-EIP2) used to configure its priority level. Low priority is the default. If two interrupts are recognized simultaneously, the interrupt with the higher priority is serviced first. If both interrupts have the same priority level, a fixed priority order is used to arbitrate, given in Table 11.4.

11.3.4. Interrupt Latency

Interrupt response time depends on the state of the CPU when the interrupt occurs. Pending interrupts are sampled and priority decoded each system clock cycle. Therefore, the fastest possible response time is 5 system clock cycles: 1 clock cycle to detect the interrupt and 4 clock cycles to complete the LCALL to the ISR. Additional clock cycles will be required if a cache miss occurs (see **Section "16. Branch Target Cache" on page 211** for more details). If an interrupt is pending when a RETI is executed, a single instruction is executed before an LCALL is made to service the pending interrupt. Therefore, the maximum response time for an interrupt (when no other interrupt is currently being serviced or the new interrupt is of greater priority) is when the CPU is performing an RETI instruction followed by a DIV as the next instruction, and a cache miss event also occurs. If the CPU is executing an ISR for an interrupt with equal or higher priority, the new interrupt will not be serviced until the current ISR completes, including the RETI and following instruction.



SFR Definition 14.8. PLL0FLT: PLL Filter

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value			
-	-	PLLICO1	PLLICO0	PLLLP3	PLLLP2	PLLLP1	PLLLP0	00110001			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	_			
	SFR Address: 0x										
	SFR Page: F										
Bits 7–6:	UNUSED: R	ead = 00b;	Write = don	't care.							
Bits 5–4:	PLLICO1-0:	PLL Currer	nt-Controlled	d Oscillator	Control Bits	6.					
	Selection is	based on th	ne desired o	utput freque	ency, accor	ding to the	following ta	able:			
					-	-	-				
		1 0			DLLC	04.0					
	PL				PLLIC	01-0					
		100 IVI			00						
		45-80 MF	1Z		01						
		30-60 MF	1Z		10						
		25–50 MF	lz		11						
Bite 3_0.		PLL Loon Fi	Iter Control	Rite							
Dits 5–0.	Selection is	hased on th	ne divided P	II referenc	e clock ac	cordina to t	he followin	a table:			
								g table.			
	Divided	PLL Refer	ence Clock		PLLL	> 3-0					
		19–30 MF	lz		000	1					
		12.2–19.5 N	ЛНz		001	1					
		7.8–12.5 M	lHz		011	1					
		5–8 MHz	2		111	1					
				I							

Table 14.2. PLL Frequency Characteristics

-40 to +85 °C unless otherwise specified

Parameter	Conditions	Min	Тур	Max	Units					
Input Frequency		5		30	MHz					
(Divided Reference Frequency)										
PLL Output Frequency		25		100*	MHz					
*Note: The maximum operating frequency of the	e C8051F124/5/6/7 is 50 MH	*Note: The maximum operating frequency of the C8051F124/5/6/7 is 50 MHz								



Certain types of instruction data or certain blocks of code can also be excluded from caching. The destinations of RETI instructions are, by default, excluded from caching. To enable caching of RETI destinations, the CHRETI bit (CCH0CN.3) can be set to '1'. It is generally not beneficial to cache RETI destinations unless the same instruction is likely to be interrupted repeatedly (such as a code loop that is waiting for an interrupt to happen). Instructions that are part of an interrupt service routine (ISR) can also be excluded from caching. By default, ISR instructions are cached, but this can be disabled by clearing the CHISR bit (CCH0CN.2) to '0'. The other information that can be explicitly excluded from caching are the data returned by MOVC instructions. Clearing the CHMOV bit (CCH0CN.1) to '0' will disable caching of MOVC data. If MOVC caching is allowed, it can be restricted to only use slot 0 for the MOVC information (excluding cache push operations). The CHFIXM bit (CCH0TN.2) controls this behavior.

Further cache control can be implemented by disabling all cache writes. Cache writes can be disabled by clearing the CHWREN bit (CCH0CN.7) to '0'. Although normal cache writes (such as those after a cache miss) are disabled, data can still be written to the cache with a cache push operation. Disabling cache writes can be used to prevent a non-critical section of code from changing the cache contents. Note that regardless of the value of CHWREN, a Flash write or erase operation automatically removes the affected bytes from the cache. Cache reads and the prefetch engine can also be individually disabled. Disabling cache reads forces all instructions data to execute from Flash memory or from the prefetch engine. To disable cache reads, the CHRDEN bit (CCH0CN.6) can be cleared to '0'. Note that when cache reads are disabled, cache writes will still occur (if CHWREN is set to '1'). Disabling the prefetch engine is accomplished using the CHPFEN bit (CCH0CN.5). When this bit is cleared to '0', the prefetch engine will be disabled. If both CHPFEN and CHRDEN are '0', code will execute at a fixed rate, as instructions become available from the Flash memory.

Cache locations can also be pre-loaded and locked with time-critical branch destinations. For example, in a system with an ISR that must respond as fast as possible, the entry point for the ISR can be locked into a cache location to minimize the response latency of the ISR. Up to 61 locations can be locked into the cache at one time. Instructions are locked into cache by enabling cache push operations with the CHPUSH bit (CCH0LC.7). When CHPUSH is set to '1', a MOVC instruction will cause the four-byte segment containing the data byte to be written to the cache slot location indicated by CHSLOT (CCH0LC.5-0). CHSLOT is them decremented to point to the next lockable cache location. This process is called a cache push operation. Cache locations that are above CHSLOT are "locked", and cannot be changed by the processor core, as shown in Figure 16.3. Cache locations can be unlocked by using a cache pop operation. A cache pop is performed by writing a '1' to the CHPOP bit (CCH0LC.6). When a cache pop is initiated, the value of CHSLOT is incremented. This unlocks the most recently locked cache location, but does not remove the information from the cache. Note that a cache pop should not be initiated if CHSLOT is equal to 111110b. Doing so may have an adverse effect on cache performance. Important: Although locking cache location 1 is not explicitly disabled by hardware, the entire cache will be unlocked when CHSLOT is equal to 000000b. Therefore, cache locations 1 and 0 must remain unlocked at all times.



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R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value					
CHMSO	V			CHMSCTH				0000000					
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0						
	SFR Address: 0x9A SFR Page: F												
Bit 7:	CHMSOV: C	ache Miss I	Penalty Ov	erflow.									
	This bit indic	ates when t	he Cache	Miss Penalty	/ Accumula	tor has ov	erflowed si	nce it was					
	last written.												
	0: The Cach	e Miss Pena	alty Accum	ulator has n	ot overflowe	ed since it	was last w	ritten.					
	1: An overflo	w of the Ca	che Miss F	enalty Accu	mulator has	s occurred	since it wa	s last written.					
Bits 6–0:	CHMSCTH:	Cache Miss	s Penalty A	ccumulator	(bits 11–5)			<i></i>					
	These are bi	ts 11-5 of th	e Cache M	liss Penalty	Accumulato	or. The nex	kt four bits	(bits 4-1) are					
	stored in CH	MSCIL in t	he CCHUI	N register.		.11 .		· · · · · · · · ·					
	The Cache N	liss Penalty	ACCUMUIA	tor is increm	iented ever	y CIOCK Cy	cie that the	processor is					
	code for exe	to a cache i	niss. This d	is primarily (iseu as a ui	agnosticie	eature, whe	en optimizing					
	Writing to CH	HMSCTH cl	iu. ears the lo	wer 5 hits of	the Cache	Miss Pena	alty Accum	ilator					
	Reading from	n CHMSCT	H returns t	he current v	alue of CHN	MSTCH, a	nd latches	bits 4-1 into					
	CHMSTCL s	o that they	can be rea	d. Because	bit 0 of the	Cache Mis	ss Penalty	Accumulator					
	is not availat	ole, the Cun	nulative Mi	ss Penalty is	equal to 2	* (CCHMS	STCH:CCH	MSTCL).					
					•	•		,					

SFR Definition 16.5. FLSTAT: Flash Status

R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	-	-	-	-	-	-	FLBUSY	0000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Bit Addressable
							SFR Address SFR Page	: 0x88 : F
Bit 7–1:	Reserved.							
Bit 0:	FLBUSY: Fla	ash Busy						
	This bit indic	ates when	a Flash writ	e or erase o	operation is	in progress	S.	
	0: Flash is ic	lle or readir	ig.					
	1: Flash writ	e/erase ope	eration is cu	irrently in pr	ogress.			









NOTES:



23.1.2. Mode 1: 16-bit Counter/Timer

Mode 1 operation is the same as Mode 0, except that the counter/timer registers use all 16 bits. The counter/timers are enabled and configured in Mode 1 in the same manner as for Mode 0.

23.1.3. Mode 2: 8-bit Counter/Timer with Auto-Reload

Mode 2 configures Timer 0 or Timer 1 to operate as 8-bit counter/timers with automatic reload of the start value. TL0 holds the count and TH0 holds the reload value. When the counter in TL0 overflows from 0xFF to 0x00, the timer overflow flag TF0 (TCON.5) is set and the counter in TL0 is reloaded from TH0. If Timer 0 interrupts are enabled, an interrupt will occur when the TF0 flag is set. The reload value in TH0 is not changed. TL0 must be initialized to the desired value before enabling the timer for the first count to be correct. When in Mode 2, Timer 1 operates identically to Timer 0.

Both counter/timers are enabled and configured in Mode 2 in the same manner as Mode 0. Setting the TR0 bit (TCON.4) enables the timer when either GATE0 (TMOD.3) is logic 0 or when the input signal /INT0 is low







23.2.4. Toggle Output Mode (Timer 2 and Timer 4 Only)

Timers 2 and 4 have the capability to toggle the state of their respective output port pins (T2 or T4) to produce a 50% duty cycle waveform output. The port pin state will change upon the overflow or underflow of the respective timer (depending on whether the timer is counting *up* or *down*). The toggle frequency is determined by the clock source of the timer and the values loaded into RCAPnH and RCAPnL. When counting DOWN, the auto-reload value for the timer is 0xFFFF, and underflow will occur when the value in the timer matches the value stored in RCAPnH:RCAPnL. When counting UP, the auto-reload value for the timer is RCAPnH:RCAPnL, and overflow will occur when the value in the timer transitions from 0xFFFF to the reload value.

To output a square wave, the timer is placed in reload mode (the Capture/Reload Select Bit in TMRnCN and the Timer/Counter Select Bit in TMRnCN are cleared to '0'). The timer output is enabled by setting the Timer Output Enable Bit in TMRnCF to '1'. The timer should be configured via the timer clock source and reload/underflow values such that the timer overflow/underflows at 1/2 the desired output frequency. The port pin assigned by the crossbar as the timer's output pin should be configured as a digital output (see **Section "18. Port Input/Output" on page 235**). Setting the timer's Run Bit (TRn) to '1' will start the toggle of the pin. A Read/Write of the Timer's Toggle Output State Bit (TMRnCF.2) is used to read the state of the toggle output, or to force a value of the output. This is useful when it is desired to start the toggle of a pin in a known state, or to force the pin into a desired state when the toggle mode is halted.

Equation 23.1. Square Wave Frequency (Timer 2 and Timer 4 Only)

$$F_{sq} = \frac{F_{TCLK}}{2 \times (65536 - RCAPn)}$$

Rev. 1.4



SFR Definition 24.7. PCA0CPHn: PCA0 Capture Module High Byte

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value		
								00000000		
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0			
SFR Address	SFR Address: PCA0CPH0: 0xFC, PCA0CPH1: 0xFD, PCA0CPH2: 0xEA, PCA0CPH3: 0xEC, PCA0CPH4: 0xEE, PCA0CPH5: 0xE2									
SFR Page	PCA0CPH0: page 0, PCA0CPH1: page 0, PCA0CPH2: page 0, PCA0CPH3: page 0, PCA0CPH4: page 0, PCA0CPH5: page 0									
Bits7–0: F T	PCA0CPHn: The PCA0CF	PCA0 Cap PHn registe	ture Module r holds the	e High Byte high byte (l	MSB) of the	e 16-bit cap	ture module	e n.		



25.1. Boundary Scan

The DR in the Boundary Scan path is an 134-bit shift register. The Boundary DR provides control and observability of all the device pins as well as the SFR bus and Weak Pullup feature via the EXTEST and SAMPLE commands.

Bit	Action	Target					
0	Capture	Reset Enable from MCU (64-pin TQFP devices)					
	Update	Reset Enable to RST pin (64-pin TQFP devices)					
1	Capture	Reset input from RST pin (64-pin TQFP devices)					
	Update	Reset output to RST pin (64-pin TQFP devices)					
2	Capture	Reset Enable from MCU (100-pin TQFP devices)					
	Update	Reset Enable to RST pin (100-pin TQFP devices)					
3	Capture	Reset input from RST pin (100-pin TQFP devices)					
	Update	Reset output to RST pin (100-pin TQFP devices)					
4	Capture	External Clock from XTAL1 pin					
	Update	Not used					
5	Capture	Weak pullup enable from MCU					
	Update	Weak pullup enable to Port Pins					
6, 8, 10, 12, 14,	Capture	P0.n output enable from MCU (e.g. Bit6=P0.0, Bit8=P0.1, etc.)					
16, 18, 20	Update	P0.n output enable to pin (e.g. Bit6=P0.0oe, Bit8=P0.1oe, etc.)					
7, 9, 11, 13, 15,	Capture	P0.n input from pin (e.g. Bit7=P0.0, Bit9=P0.1, etc.)					
17, 19, 21	Update	P0.n output to pin (e.g. Bit7=P0.0, Bit9=P0.1, etc.)					
22, 24, 26, 28, 30,	Capture	P1.n output enable from MCU					
32, 34, 36	Update	P1.n output enable to pin					
23, 25, 27, 29, 31,	Capture	P1.n input from pin					
33, 35, 37	Update	P1.n output to pin					
38, 40, 42, 44, 46,	Capture	P2.n output enable from MCU					
48, 50, 52	Update	P2.n output enable to pin					
39, 41, 43, 45, 47,	Capture	P2.n input from pin					
49, 51, 53	Update	P2.n output to pin					
54, 56, 58, 60, 62,	Capture	P3.n output enable from MCU					
64, 66, 68	Update	P3.n output enable to pin					
55, 57, 59, 61, 63,	Capture	P3.n input from pin					
65, 67, 69	Update	P3.n output to pin					
70, 72, 74, 76, 78,	Capture	P4.n output enable from MCU					
80, 82, 84	Update	P4.n output enable to pin					
71, 73, 75, 77, 79,	Capture	P4.n input from pin					
81, 83, 85	Update	P4.n output to pin					
86, 88, 90, 92, 94,	Capture	P5.n output enable from MCU					
96, 98, 100	Update	P5.n output enable to pin					
87, 89, 91, 93, 95,	Capture	P5.n input from pin					
97, 99, 101	Update	P5.n output to pin					
102, 104, 106,	Capture	P6.n output enable from MCU					
108, 110, 112, 114,	Update	P6.n output enable to pin					
116	.						

Table 25.1. Boundary Data Register Bit Definitions

EXTEST provides access to both capture and update actions, while Sample only performs a capture.



JTAG Register Definition 25.3. FLASHCON: JTAG Flash Control

								Reset Value			
SFLE	WRMD2	WRMD1	WRMD0	RDMD3	RDMD2	RDMD1	RDMD0	00000000			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0				
This register determines how the Flash interface logic will respond to reads and writes to the FLASH- DAT Register.											
Bit7:	SFLE: Scratchpad Flash Memory Access Enable When this bit is set, Flash reads and writes are directed to the two 128-byte Scratchpad Flash sectors. When SFLE is set to logic 1, Flash accesses out of the address range 0x00- 0xFF should not be attempted (with the exception of address 0x400, which can be used to simultaneously erase both Scratchpad areas). Reads/Writes out of this range will yield undefined results. 0: Flash access directed to the Program/Data Flash sector.										
Bits6–4:	 WRMD2-0: Write Mode Select Bits. The Write Mode Select Bits control how the interface logic responds to writes to the FLASH-DAT Register per the following values: 000: A FLASHDAT write replaces the data in the FLASHDAT register, but is otherwise ignored. 001: A FLASHDAT write initiates a write of FLASHDAT into the memory address by the FLASHADR register. FLASHADR is incremented by one when complete. 010: A FLASHDAT write initiates an erasure (sets all bytes to 0xFF) of the Flash page containing the address in FLASHADR. The data written must be 0xA5 for the erase to occur. FLASHADR is not affected. If FLASHADR = 0x1FBFE – 0x1FBFF, the entire user space will be erased (i.e. entire Flash memory except for Reserved area 0x1FC00 – 0x1FFFF). 										
Bits3–0:	 RDMD3–0: Read Mode Select Bits. The Read Mode Select Bits control how the interface logic responds to reads from the FLASHDAT Register per the following values: 0000: A FLASHDAT read provides the data in the FLASHDAT register, but is otherwise ignored. 0001: A FLASHDAT read initiates a read of the byte addressed by the FLASHADR register if no operation is currently active. This mode is used for block reads. 0010: A FLASHDAT read initiates a read of the byte addressed by FLASHADR only if no operation is active and any data from a previous read has already been read from FLASHDAT. This mode allows single bytes to be read (or the last byte of a block) without initiating an extra read. (All other values for RDMD3–0 are reserved.) 										

